



**THE DATASHEET OF  
DMP4025LSD-13**



**40V DUAL P-CHANNEL ENHANCEMENT MODE MOSFET**

**Product Summary**

$V_{(BR)DSS}$	$R_{DS(on)}$ max	$I_D$ max (A) $T_A = +25^\circ C$
-40V	25m $\Omega$ @ $V_{GS} = -10V$	-7.6
	45m $\Omega$ @ $V_{GS} = -4.5V$	-6.0

**Description**

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

**Applications**

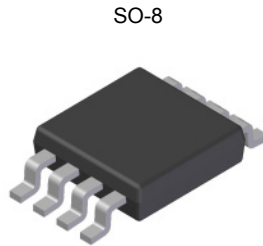
- Motor Control
- Backlighting
- DC-DC Converters
- Printer Equipment

**Features and Benefits**

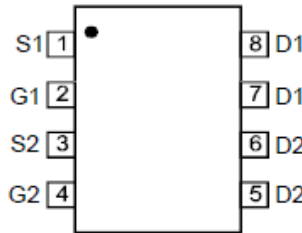
- Low  $R_{DS(on)}$  – Minimizes conduction losses
- Fast switching speed – Minimizes switching losses
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

**Mechanical Data**

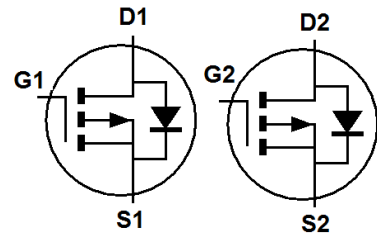
- Case: SO-8
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208E3
- Weight: 0.074 grams (approximate)



Top View



Top View Pin-Out



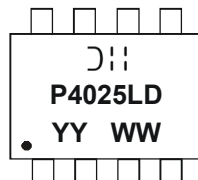
Device symbol

**Ordering Information** (Notes 4 & 5)

Part Number	Compliance	Case	Packaging
DMP4025LSD-13	Standard	SO-8	2500 / Tape & Reel
DMP4025LSDQ-13	Automotive	SO-8	2500 / Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.
  5. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to [http://www.diodes.com/quality/product\\_grade\\_definitions/](http://www.diodes.com/quality/product_grade_definitions/).

**Marking Information**



- ☺ :: = Manufacturer's Marking
- P4025LD = Product Type Marking Code
- YYWW = Date Code Marking
- YY = Year (ex: 10 = 2010)
- WW = Week (01 - 53)

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

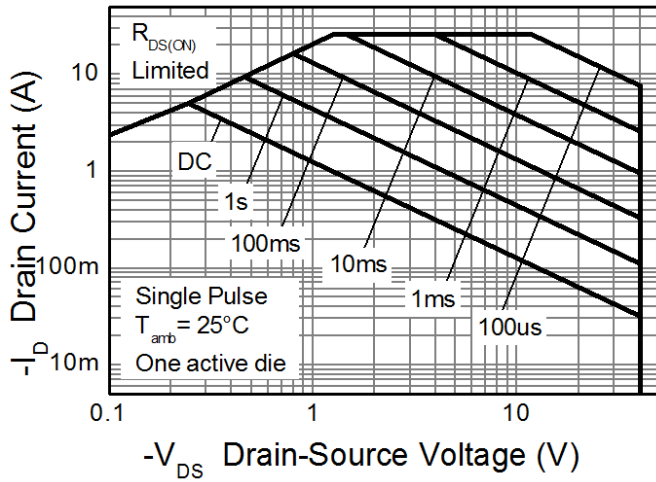
Characteristic		Symbol	Value	Units	
Drain-Source Voltage		$V_{DSS}$	-40	V	
Gate-Source Voltage		$V_{GSS}$	$\pm 20$		
Continuous Drain Current	$V_{GS} = -10\text{V}$	(Notes 7 & 9)	-7.6	A	
		$T_A = +70^\circ\text{C}$ (Notes 7 & 9)	-6.1		
		(Notes 6 & 9)	-5.8		
		(Notes 6 & 10)	-6.9		
Pulsed Drain Current	$V_{GS} = -10\text{V}$	(Notes 8 & 9)	$I_{DM}$		-28.0
Continuous Source Current (Body diode)		(Notes 7 & 9)	$I_S$		-3.0
Pulsed Source Current (Body diode)		(Notes 8 & 9)	$I_{SM}$	-28.0	

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

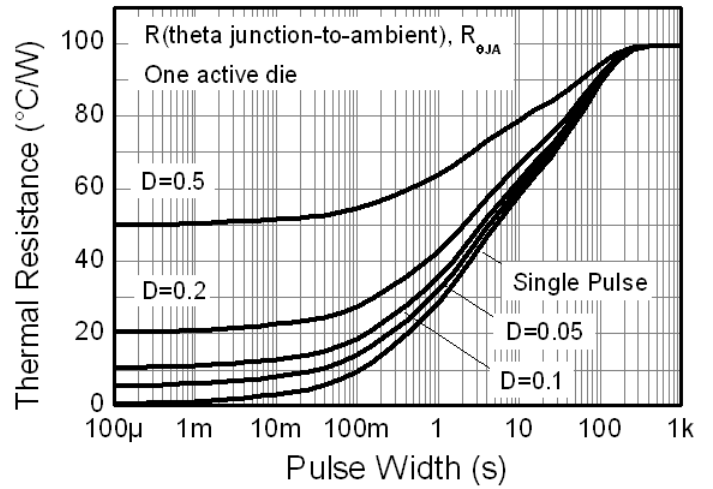
Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Notes 6 & 9)	$P_D$	1.25 10	W mW/ $^\circ\text{C}$
	(Notes 6 & 10)		1.8 14.3	
	(Notes 7 & 9)		2.14 17.2	
Thermal Resistance, Junction to Ambient	(Notes 6 & 9)	$R_{\theta JA}$	100	$^\circ\text{C/W}$
	(Notes 6 & 10)		70	
	(Notes 7 & 9)		58	
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	$R_{\theta JL}$	51	$^\circ\text{C/W}$
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

- Notes:
6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  7. Same as note (2), except the device is measured at  $t \leq 10$  sec.
  8. Same as note (2), except the device is pulsed with  $D = 0.02$  and pulse width 300 $\mu\text{s}$ .
  9. For a dual device with one active die.
  10. For a device with two active die running at equal power.
  11. Thermal resistance from junction to solder-point (at the end of the drain lead).

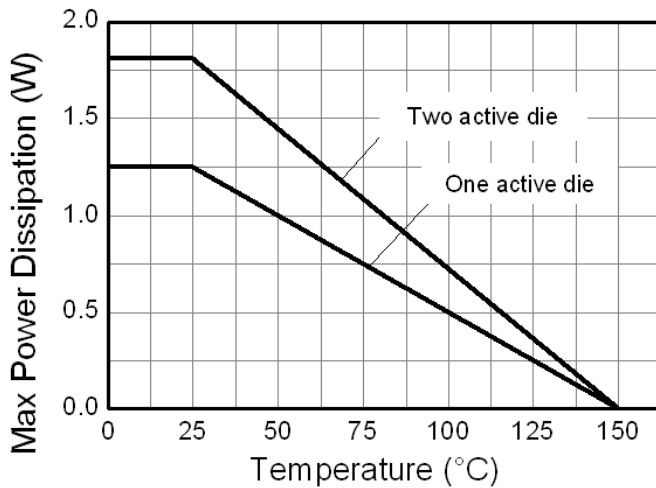
**Thermal Characteristics**



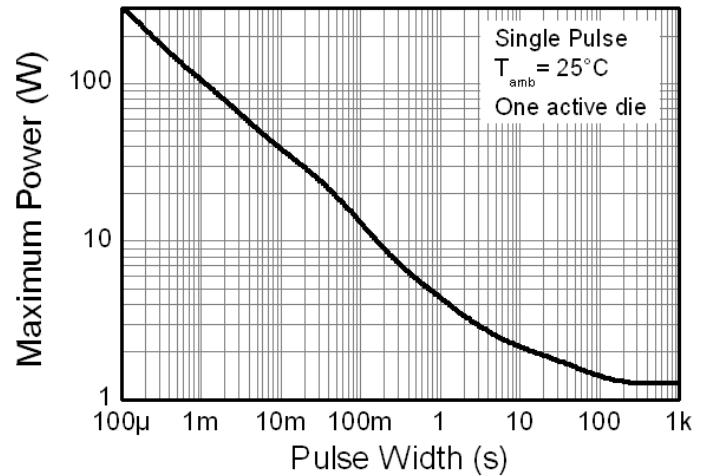
**P-channel Safe Operating Area**



**Transient Thermal Impedance**



**Derating Curve**



**Pulse Power Dissipation**

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DS}$	-40	—	—	V	$I_D = -250\mu\text{A}$ , $V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	$I_{DSS}$	—	—	-1.0	$\mu\text{A}$	$V_{DS} = -40\text{V}$ , $V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(th)}$	-0.8	-1.3	-1.8	V	$I_D = -250\mu\text{A}$ , $V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 12)	$R_{DS(ON)}$	—	18	25	m $\Omega$	$V_{GS} = -10\text{V}$ , $I_D = -3\text{A}$
			30	45		$V_{GS} = -4.5\text{V}$ , $I_D = -3\text{A}$
Forward Transconductance (Notes 12 & 13)	$g_{fs}$	—	16.6	—	S	$V_{DS} = -5\text{V}$ , $I_D = -3\text{A}$
Diode Forward Voltage (Note 12)	$V_{SD}$	—	-0.7	-1.0	V	$I_S = -1\text{A}$ , $V_{GS} = 0\text{V}$
<b>DYNAMIC CHARACTERISTICS (Note 13)</b>						
Input Capacitance	$C_{iss}$	—	1640	—	pF	$V_{DS} = -20\text{V}$ , $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
Output Capacitance	$C_{oss}$	—	179	—		
Reverse Transfer Capacitance	$C_{rss}$	—	128	—		
Gate Resistance	$R_g$	—	6.43	—	$\Omega$	$V_{DS} = 0\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$
Total Gate Charge (Note 14)	$Q_g$	—	14.0	—	nC	$V_{GS} = -4.5\text{V}$ $V_{DS} = -20\text{V}$ $I_D = -3\text{A}$
Total Gate Charge (Note 14)	$Q_g$	—	33.7	—		
Gate-Source Charge (Note 14)	$Q_{gs}$	—	5.5	—		
Gate-Drain Charge (Note 14)	$Q_{gd}$	—	7.3	—		
Turn-On Delay Time (Note 14)	$t_{D(on)}$	—	6.9	—	ns	$V_{DD} = -20\text{V}$ , $V_{GS} = -10\text{V}$ $I_D = -3\text{A}$
Turn-On Rise Time (Note 14)	$t_r$	—	14.7	—		
Turn-Off Delay Time (Note 14)	$t_{D(off)}$	—	53.7	—		
Turn-Off Fall Time (Note 14)	$t_f$	—	30.9	—		

Notes: 12. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$   
 13. For design aid only, not subject to production testing.  
 14. Switching characteristics are independent of operating junction temperatures.

**Typical Characteristics**

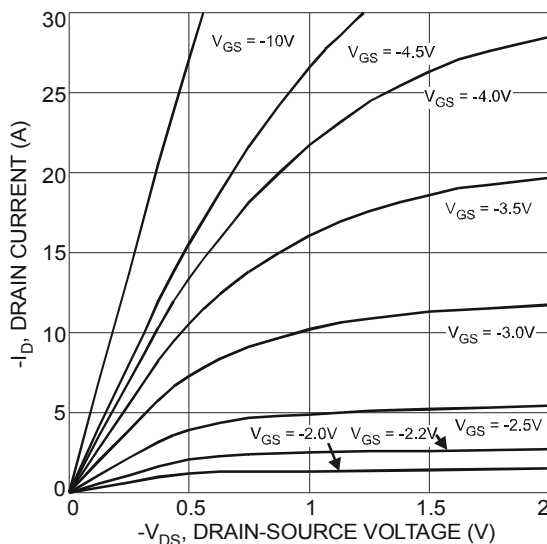


Fig. 1 Typical Output Characteristic

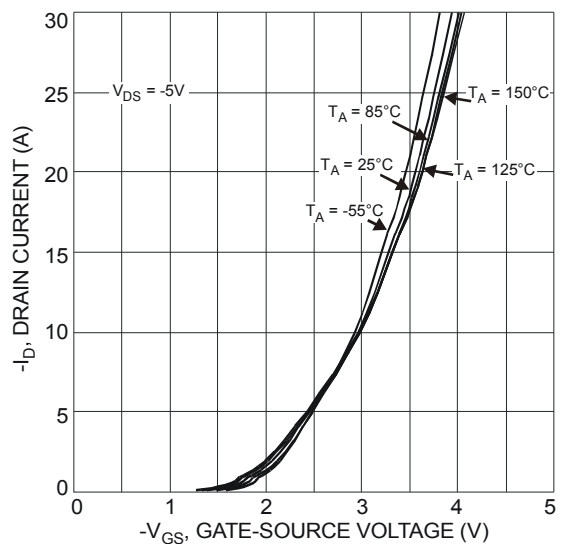


Fig. 2 Typical Transfer Characteristic

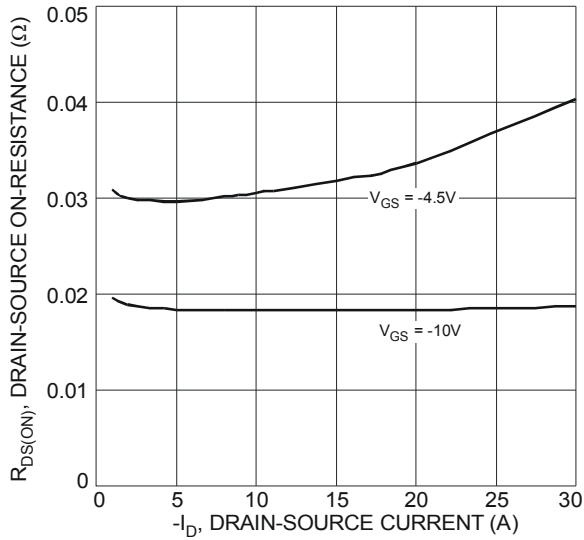


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

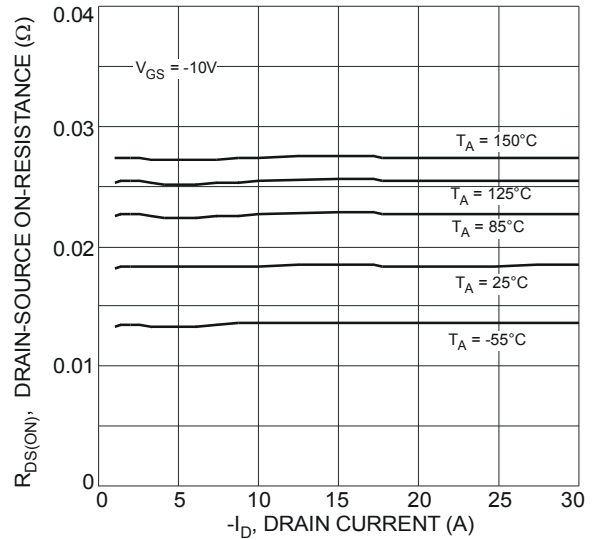


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

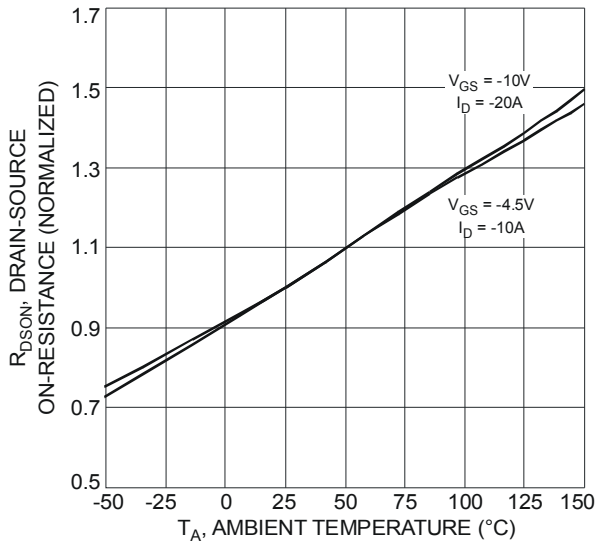


Fig. 5 On-Resistance Variation with Temperature

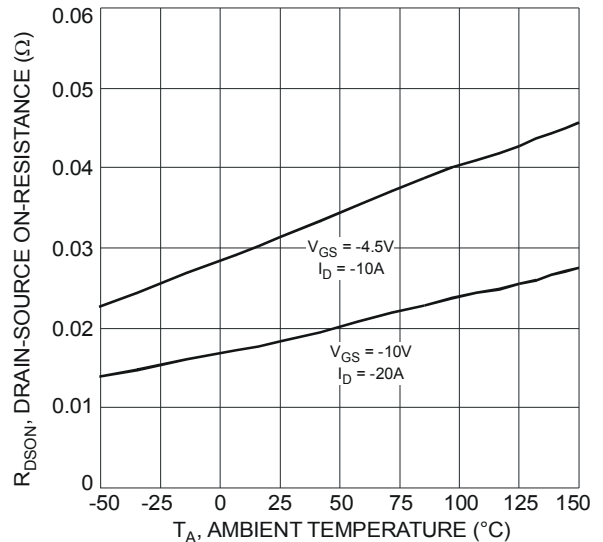


Fig. 6 On-Resistance Variation with Temperature

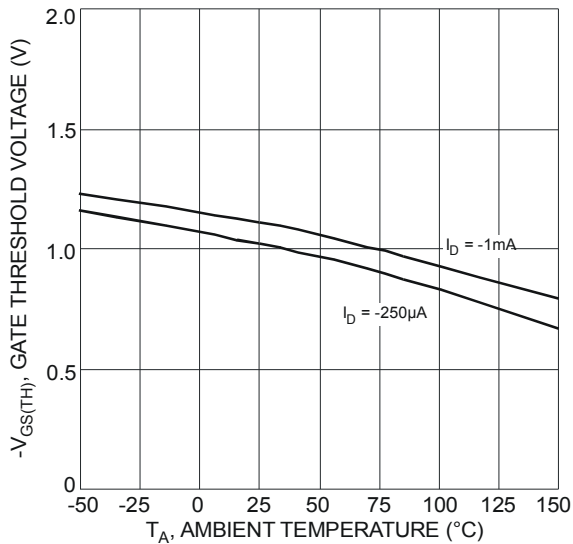


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

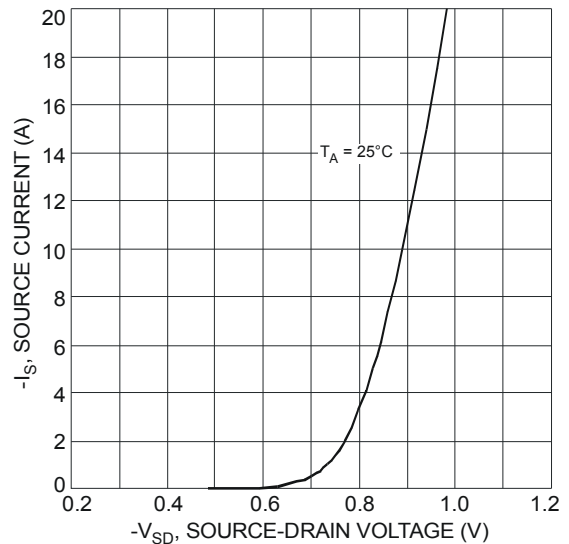
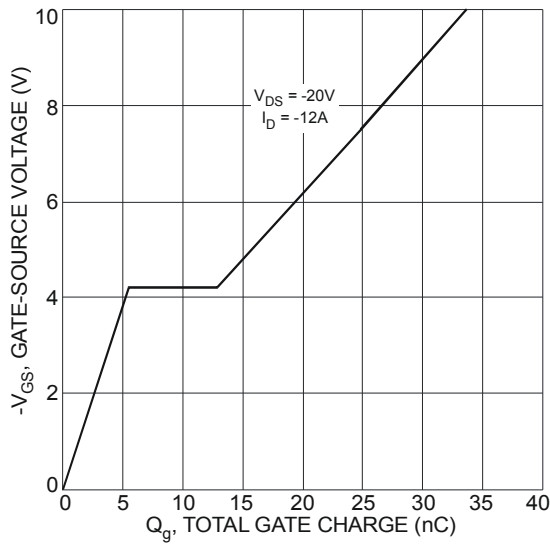
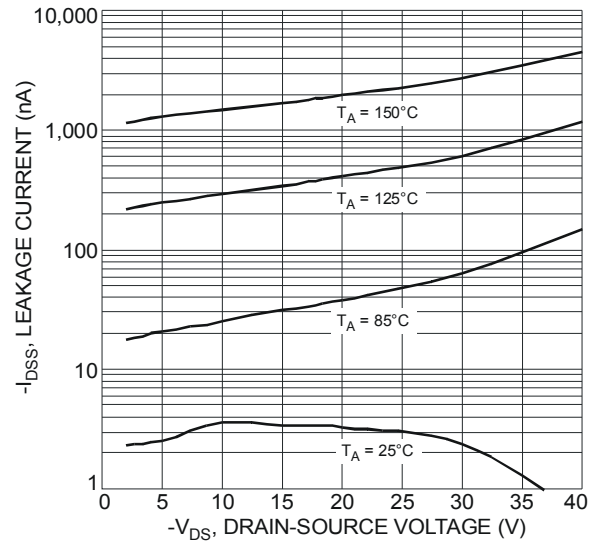
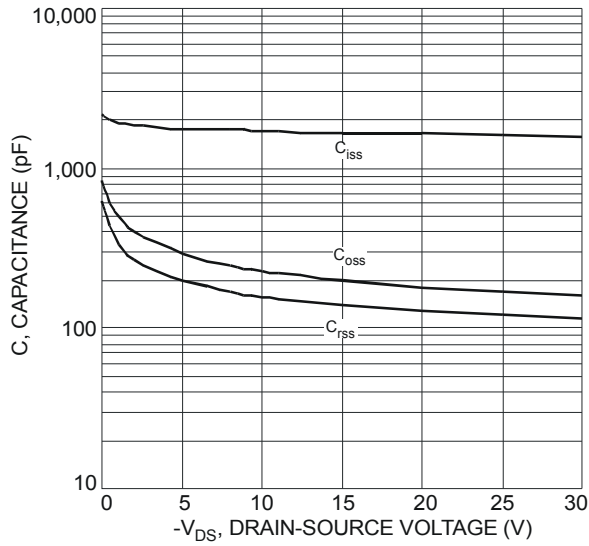


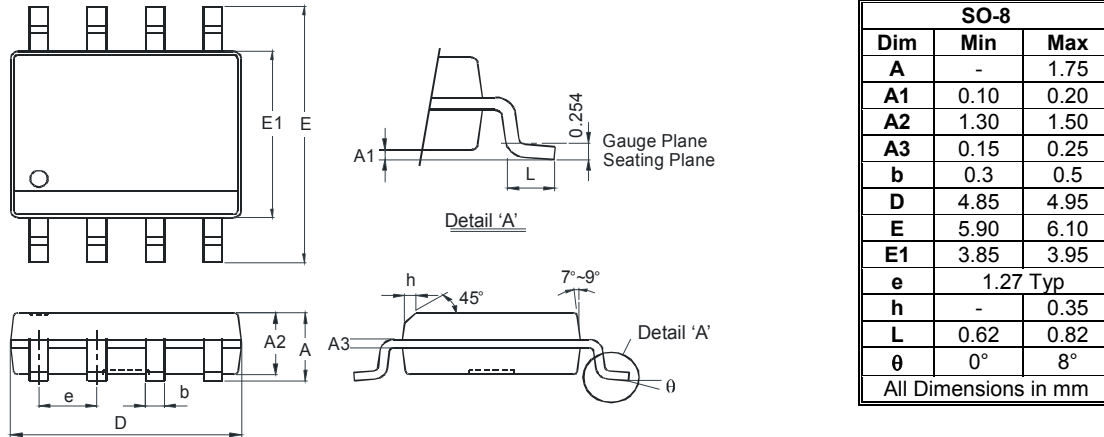
Fig. 8 Diode Forward Voltage vs. Current

**DMP4025LSD**



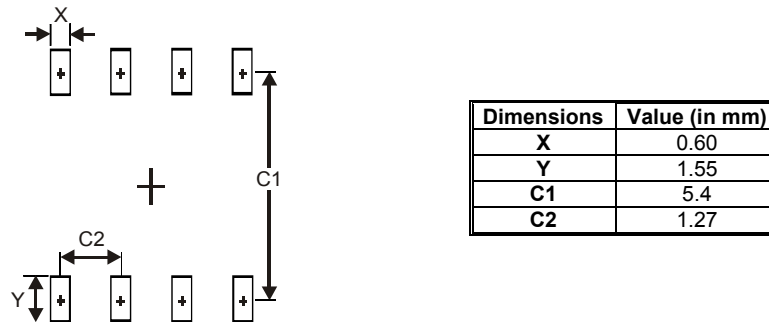
## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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